## **Material Declaration Form**

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ams-OSRAM AG Tobelbader Strasse 30 A-8141 Premstaetten, Austria Tel +43 (0) 3136 500-0



Ordering Code	Production Version	Package Family	Assembly Material Number	Lead Count	Weight Manufacturing (mg) Country	Halogen Free	EU RoHS	China Rohs	Release Status	Report Version
AS5116-HSOM	512160034P1	XDLF IDF SOIC; 150	512160034	8	80.6	YES	YES	YES	PROTOS	1

Production Version: 512160034P1

Homogenous Material	Weight (mg)	Symbol	Chemical Substance	Input Ratio (%)	CAS Number	Unit Weight (mg)	Unit Weight (%)	Amount (ppm)
IC	5.4	Si	Silicon	100.00	7440-21-3	5.40000	6.69975	66998
		Subtotal:		100.00		5.40000	6.69975	66998
Leadframe	28.9	Ag	Silver	0.30	7440-22-4	0.08670	0.10757	1076
		Cu	Copper	95.90	7440-50-8	27.71510	34.38598	343860
		Mg	Magnesium	0.15	7439-95-4	0.04335	0.05378	538
		Ni	Nickel	3.00	7440-02-0	0.86700	1.07568	10757
		Si	Silicon	0.65	7440-21-3	0.18785	0.23306	2331
		Subtotal:		100.00		28.90000	35.85608	358561
Leadframe (Internal Plating)	0.2	Ag	Silver	100.00	7440-22-4	0.20000	0.24814	2481
		Subtotal:		100.00		0.20000	0.24814	2481
Plating	0.9	Sn	Tin	100.00	7440-31-5	0.90000	1.11663	11166
		Subtotal:		100.00		0.90000	1.11663	11166

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AS5116-HSOM	512160034P1	XDLF IDF SOIC; 150	512160034	8	80.6	YES	YES	YES	PROTOS	1

Production Version: 512160034P1

Homogenous Material	Weight (mg)	Symbol	Chemical Substance	Input Ratio (%)	CAS Number	Unit Weight (mg)	Unit Weight (%)	Amount (ppm)
Adhesive	0.4	Ag	Silver	79.00	7440-22-4	0.31600	0.39206	3921
		C15H16O2	Reaction product: bisphenol-A- (epichlorhydrin); epoxy resin	1.00	25068-38-6	0.00400	0.00496	50
			Epoxy Resin	5.00	Proprietary	0.02000	0.02481	248
			Formaldehyde, polymer with aniline, maleated, cyclized	10.00	67784-74-1	0.04000	0.04963	496
			Modified Resin	5.00	Proprietary	0.02000	0.02481	248
		Subtotal:		100.00		0.40000	0.49628	4963
Wire	0.1	Au	Gold	99.00	7440-57-5	0.09900	0.12283	1228
		Pd	Palladium	1.00	7440-05-3	0.00100	0.00124	12
		Subtotal:		100.00		0.10000	0.12407	1241
Moldcompound	44.7	SiO2	Silica Fused	86.00	60676-86-0	38.44200	47.69479	476948
			Carbon Black	0.50	1333-86-4	0.22350	0.27730	2773
			Epoxy Resin	7.50	25928-94-3	3.35250	4.15943	41594
			Phenol Resin	6.00	28064-14-4	2.68200	3.32754	33275
		Subtotal:		100.00		44.70000	55.45906	554591
Total:	80.6					80.60	100.00000	1000000

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